

01-21-05

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Dated: January 18, 2005

Signature:

Jean Bove

Ref.: 7452-105/10313554  
(PATENT)

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Patent Application of:  
Shih-Ping Hsu

Confirmation No.: 6002

Application No.: 10/695,356

Group Art Unit: 2812

Filed: October 27, 2003

Examiner: Berezny, Nema O.

For: SEMICONDUCTOR PACKAGE  
SUBSTRATE HAVING CONTACT PAD  
PROTECTIVE LAYER FORMED THEREON  
AND METHOD FOR FABRICATING THE  
SAME

**RESPONSE**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

In response to the Office Action mailed October 14, 2004, the following response is submitted.

**Arguments/remarks begin on page 2.**